

DESCRIPTION	Standard	Advanced
Layers number	1-18 Layers PCB	1-36 Layers PCB
Max. Panel Size	500x600mm( 19.68"x 23.62")	upon request
Max.Board Thickness	3,2 mm	8.5mm
Min. Board Thickness	2L:0.2mm	2L:0.1mm
	4L:0.4mm	4L:0.3mm
	6L:0.8mm	6L:0.6mm
Min Inner Layer Clearance	0,102mm (4mil)	0,0762mm (3mil)
Min Line width	0,127 mm (5 mil)	0,0762mm (3mil)
Min Line space	0,127 mm (5 mil)	0,0762mm (3mil)
Min.Hole Size	0.125mm	0.1mm
Min plated hole thickness	20 $\mu$ m	25 $\mu$ m
Min Blind/Buried hole size	0.1 mm	0.1mm(1-18layers)
PTH Dia. Tolerance	$\pm$ 0.076mm ( $\pm$ 3mil)	$\pm$ 0.076mm ( $\pm$ 3mil)
Non PTH Dia. Tolerance < 6,5mm	$\pm$ 0.05mm ( $\pm$ 2mil)	$\pm$ 0.05mm ( $\pm$ 2mil)
Hole Position Deviation	$\pm$ 0.05mm ( $\pm$ 2mil)	$\pm$ 0.05mm( $\pm$ 2mil)
Base Copper	17 $\pm$ 210 $\mu$ m	9 $\pm$ 210 $\mu$ m
Heavy Copper	140 $\mu$ m ( 4 Oz)	175 $\mu$ m ( 6 Oz)
Aspect Ratio (PTH)	08:01	13:01
Aspect Ratio ( Blind holes)	01:01	01:01
Soldermask colour	Green,black,Blue,White,Yellow,Red	Green,black,Blue,White,Yellow,Red
Silkscreen colour	White,Yellow,Red, Black	White,Yellow,Red,Black
Outline	Routing,V-Groove, Scoring, Beveling ,	Routing,V-Groove, Scoring, Beveling ,
Outline RoutingTolerance	$\pm$ 0.10mm $\pm$ 5mil	$\pm$ 0.05mm ( $\pm$ 2mil)
Peelable Mask	Top,bottom,double sided	Top,bottom,double sided
Controlled Impedance	+/- 10%	+/- 7%
Final Thickness Tolerance	+/- 10%	+/- 5%
Scoring ( V Cut angle )	30°	30°
Scoring (Fr4 tolerance )	+/-0,10 mm ( 4mils)	+/-0,10 mm ( 4mils)
Mechanical holes Inter axes	+/-0,10 mm ( 4mils)	+/-0,10 mm ( 4mils)
Warp and Twist	$\leq$ 0.7%	$\leq$ 0.7%
Plated Slot ( tolerance)	+/-0,10 mm ( 4mils)	+/-0,10 mm ( 4mils)
Peel Strength	1.4 N/mm	1.4N/mm
Solder Mask Abrasion	> 6H	>6H
Solder Mask Bridge	100 $\mu$ m ( green) 130 $\mu$ m others colors	80 $\mu$ m ( green) 120 $\mu$ m others colors
Flammability	94V-0	94V-0
Test Voltage	10-250V	10-250V
Minimum pad testable	100 $\mu$ m	100 $\mu$ m
Material Fr4	Low TG 135°	High CTI >400 V
	Medium TG 145° $\pm$ 170°	HDI Fr4 material
	High TG > 170 °	High TG Halogen Free

DESCRIPTION	Standard	Advanced
PTFE Laminates	Arlon	Diclad- AD series
	Taconic	TP-TPG-TPN series
	Rogers	4350-4003-others
IMS ( Aluminium)	Bergquwist	all series
	Ventec	all series
	Others	upon request
FLEXIBLE FLEX FLEX	RIGID- SEMI-	Kapton Poliyimide
		all series
		all series
Fr4 - IS410	Fr4 - Kapton -Poliyimide	all series
		all series
		all series
Hibrid Laminating	Fr4- Rogers- Arlon	upon request
FINISHES -HASL (IPC 6012 )	Sn\Pb ;Thickness= 1-40 µm ; shelf life 12 months ; suitable for pitch or BGA > 0,90mm	
FINISHES -HASL Lead Free (IPC 6012 )	Sn100 ;Thickness= 1-40 µm ; shelf life 12 months ; not suitable for pitch or BGA < 0,90mm ; RoHs Compliant	
FINISHES -ENIG (IPC 4552 )	Ni\Au ;Thickness Ni= 3-8 µm Au = 0,05-0,08 µm ; shelf life 6 months ; reccomended for fine pitch and micro	
FINISHES -Chemical Tin (IPC 4554 )	Im Sn ;Thickness = 0,8 ±1,20 µm ; shelf life 3 months ; reccomended for press fit ; RoHs Compliant	
FINISHES -Chemical Silver (IPC 4553)	Im Ag ;Thickness = 0,2 ±0,60 µm ; shelf life 3 months ; reccomended for press fit ; RoHs Compliant	
FINISHES -OSP Organic Solder Perservative (IPC 2221)	Cu ;Thickness = in Armstrong ; shelf life 3 months ; reccomended for wettability ; RoHs Compliant	
FINISHES HARD GOLD (IPC 4552 )	Ni\Au ;Thickness Ni= 3-8 µm Au = 0,8-1,20 µm ; shelf life 6 months ; reccomended for SLIDING CONTACT ;	
FINISHES -ENEPIG (IPC 4552 )	Ni\Pd\Au ;Thickness Ni= 3-8 µm Pd= 0,05 ±0,15 µm Au = 0,05-0,08 µm ; shelf life 6 months ; reccomended for	
FINISHES -SPECIAL	Carbon - PTF technology -Flash Gold- Electrolytic Silver- Others	upon request
PCB SPECIAL TECHNOLOGY	Capped vias ; Insert Coin ; Filling vias ; laser drilling, Laser Blind ; Blind& Buried vias ; vias in pad ; Others	upon request

